

Recommended application guide for UHB Foamed Acrylic Tapes & Double Sided Tape Systems.

SURFACE PREPARATION GUIDE

Process:

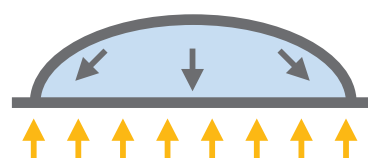
- In addition to chemical cleaning it maybe necessary to use a Glasscorp PBSA abrasive pad to prepare surfaces such as bare metals, heavily contaminated surfaces, remove old paint, rust and oxides. Please ensure to remove all dust with a lint-free wipe.

Please see diagram below for surface degree of difficulty.

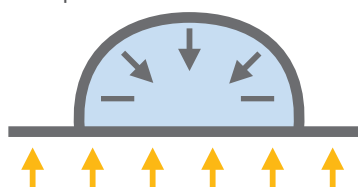
SPECIAL CONSIDERATIONS

- Low Surface Energy substrates may need to be chemically primed before tape application to ensure an effective bonding surface.
- Most porous surfaces such as concrete, wood, plaster, and fabrics need to be sealed for effective tape bonding. Ensure that any sealers used are fully cured prior to applying the tape.
- Some materials such as copper, bronze, lead and plasticized vinyl may need to be sealed or primed prior to applying the tape.
- Glass surfaces may need to be primed especially if used in high humidity conditions.
- Best bonding results are generally achieved on smooth surfaces, however on textured or uneven substrates it is important to select and test a suitable tape with a thicker carrier and a heavier adhesive mass.

Easy to adhere
- good adhesive “wet out”



Hard to adhere
- poor adhesive “wet out”



Flexible PVC, Polystyrene, Acetal, EVA,
Polyethylene (PE), Polypropylene (PP),
Tedlar (PVF), Powder Coated Paints,
Teflon, EPDM Foams

To Bond to

Easy

Difficult



APPLICATION PRESSURE

The bond strength is a direct function of the contact between the adhesive and the substrates. Good surface contact is attained by high application pressure, which can be obtained, for instance, by using a squeegee, pressure roller or pressure fixture. Generally this results in a better bonding contact than the application by hand. The way the pressure is applied and the amount of pressure depend on the materials used. It is therefore necessary to co-ordinate the application pressure parameters with the materials.

Please bear in mind that, depending on the adhesive system used, it may take up to 72 hours to obtain the final bond strength.

Please make sure that the ends of the parts to be joined are strain-free. Shear and tensile loads acting on the bonded parts must be able to spread over the entire adhesive surface. Long-lasting tensions generally have a negative impact on the bond strength.



PROCESSING / APPLICATION TEMPERATURE

Optimum processing temperatures (object temperature and ambient temperature) range from +15°C to +30°C. We do not recommend working at higher temperatures unless adhesive systems that were especially developed for that purpose are used. If the tape is applied below the recommended temperature, the adhesive may harden, compromising the desired adhesion.

The formation of condensate must always be avoided. Condensation can form only when the adhesive tape and/or the substrate is moved from a cold area to a warmer one. In such cases sufficient time should be allowed between transportation and application so that the temperatures of all parts to be joined become similar and rise to a value within the above-mentioned temperature range.



PRODUCT STORAGE

Adhesive tapes must be stored in their original packing at 20°C and relative humidity of 50%. High relative humidity and direct sunlight must be avoided at all costs. Normal storage time frame from date of manufacture is 12 months.



TAPE APPLICATION

Remember: Pressure sensitive tapes ideally require around 15psi (100 kPa) to achieve good “wet out”, however this will be affected by the smoothness of the two surfaces and the ambient temperature.

- Unwind the tape and smooth down with hand pressure, avoiding any wrinkles.
- Depending on the surface type you may need to apply a primer and/or use an abrasive pads – follow surface preparation guidelines.
- Apply firm, even pressure across the surface of the release liner with a hand pressure roller to ensure entire surface contact with no air bubbles.
- The release liner should be left on until the second surface is prepared and ready to be bonded.
- It is recommended to peel back the release liner at 90° especially if one is positioning the tape in a mounting application.
- Expose part of the tape to assist in correct positioning and remove the rest of the release liner once in place. In some cases clamping surfaces together maybe beneficial to assist in a solid bond over the curing time.

These processing instructions are based on our experience. They do not explain all bonding aspects to be taken into account. The user is expected to have subject-specific knowledge.

Because of the large number of potential influences resulting from processing, bonding and use we recommend that you conduct tests on our products before using them for special applications. This data does not imply any guarantee of specific properties.